

Fig. 1

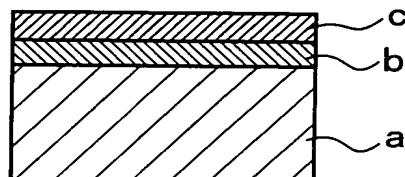


Fig. 2

Flow	Electron Beam Patterning Process	Laser Beam Patterning Process
Receipt of Blank		
Exposure/Patterning	Electron Beam Patterning Device	Laser Beam Patterning Device
Development	Spray, Dip, Paddle Systems Organic Solvent Development Alkali Development	Alkali Development
Post-Baking	Hot Plate Oven Convection Oven	Generally, any treatment is not required.
De-scumming	Plasma De-scumming Device	Generally, any treatment is not required.
CrEtching	Wet Etching and Dry-Etching	
Removal of Resist	Solvent Peeling, Ashing	Exposure of Whole Surface/Alkali Peeling, Solvent Peeling, Ashing
Washing	Sheet-Fed Acid-Treatment, Physical Scrubbing, or the like	
To Inspection Step		

FIG. 3

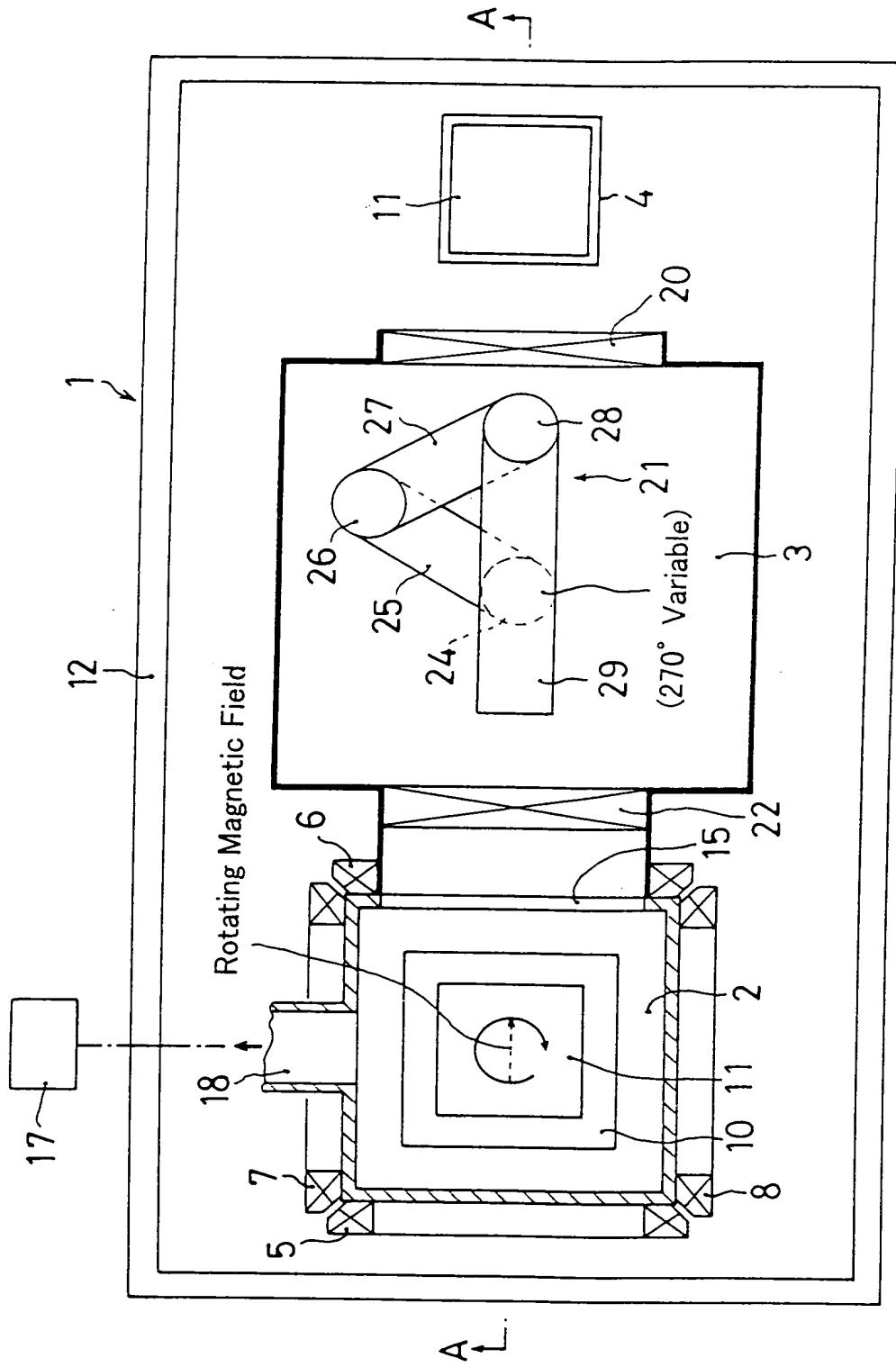
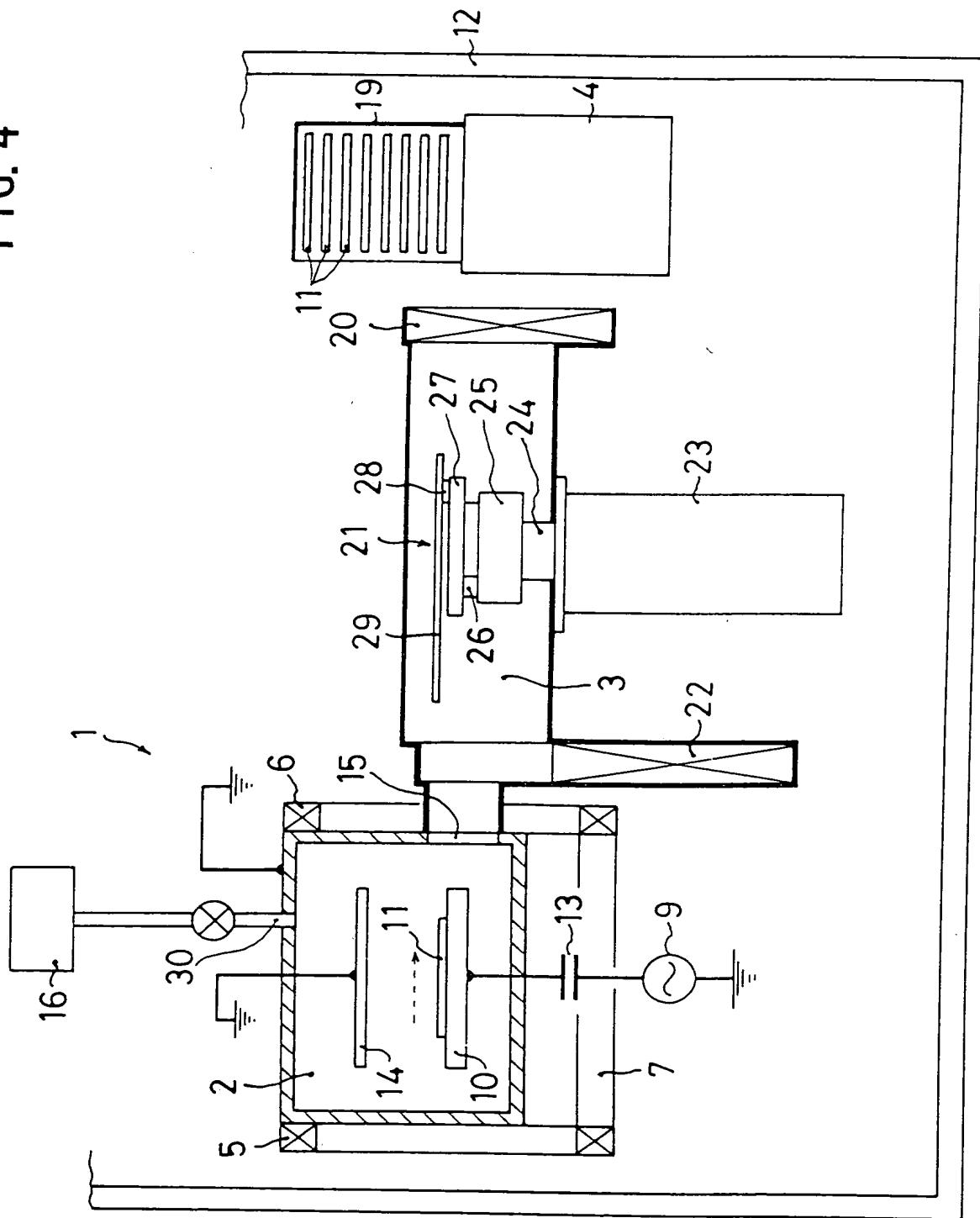
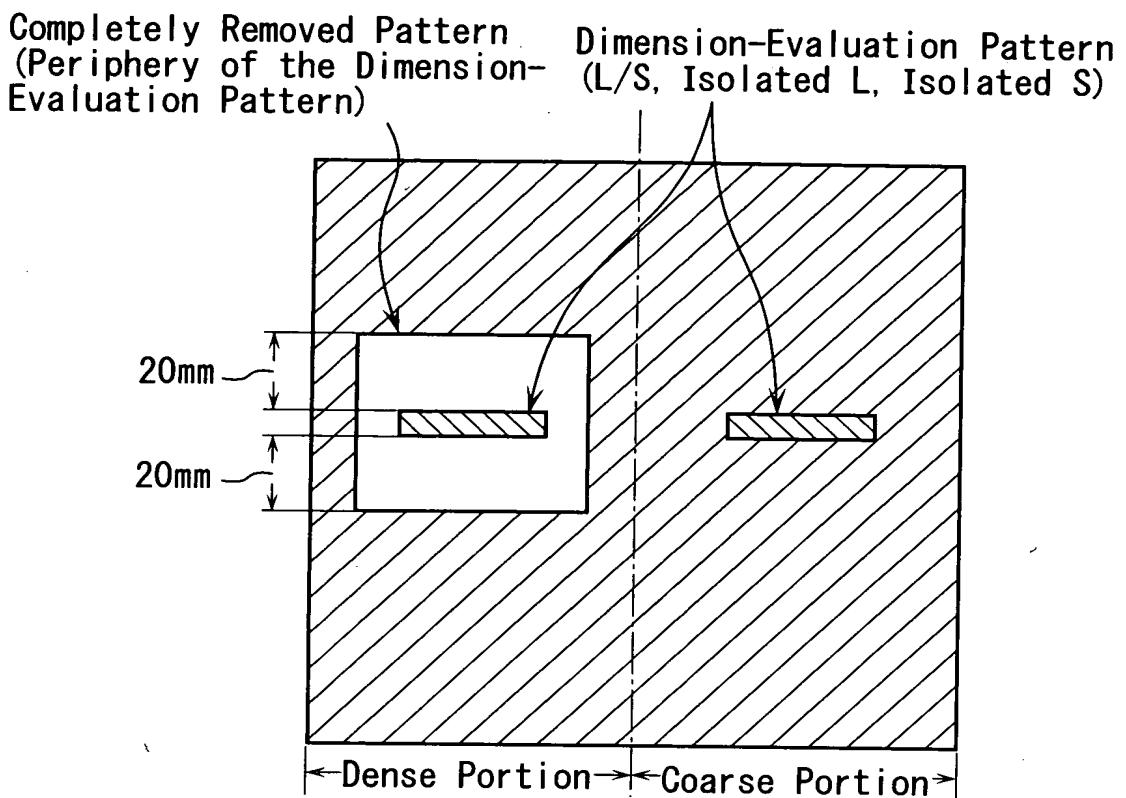


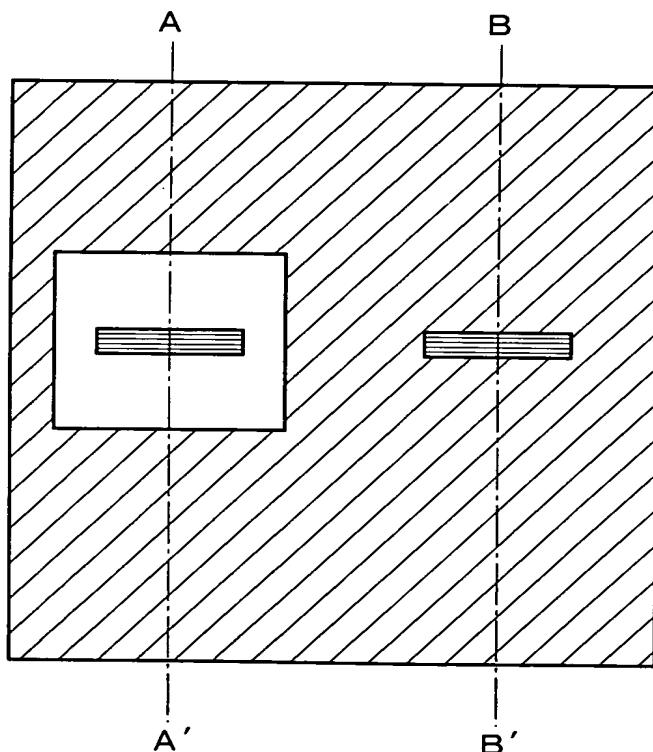
FIG. 4



Fing. 5 A



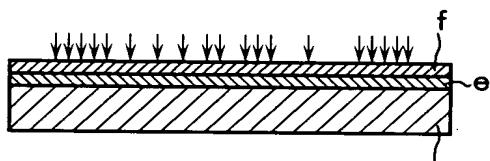
Fing. 5 B



Fing. 6 A

Test Pattern on Dense
Portion(A-A')

(a) EB Patterning



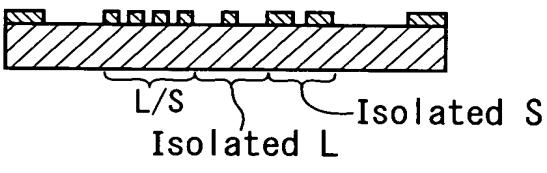
(b) Development ↓



(c) Etching ↓



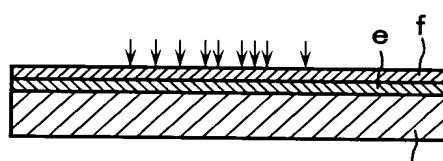
(d) Removal of Resist ↓



Fing. 6 B

Test Pattern on Coarse
Portion(B-B')

(a) EB Patterning



(b) Development ↓



(c) Etching ↓



(d) Removal of Resist ↓

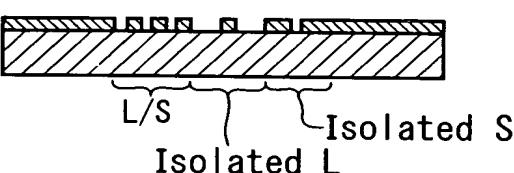


Fig. 7

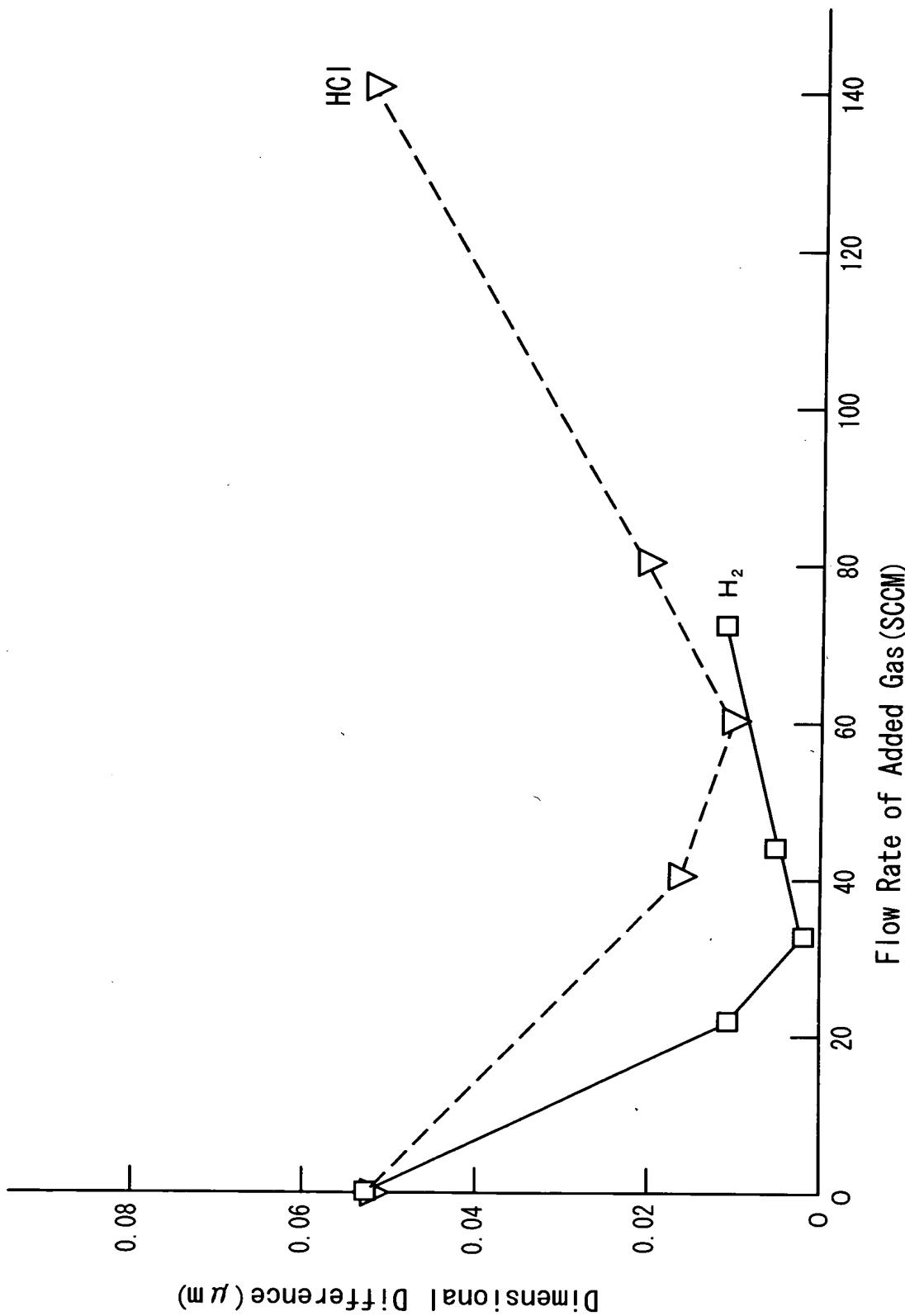


Fig. 8

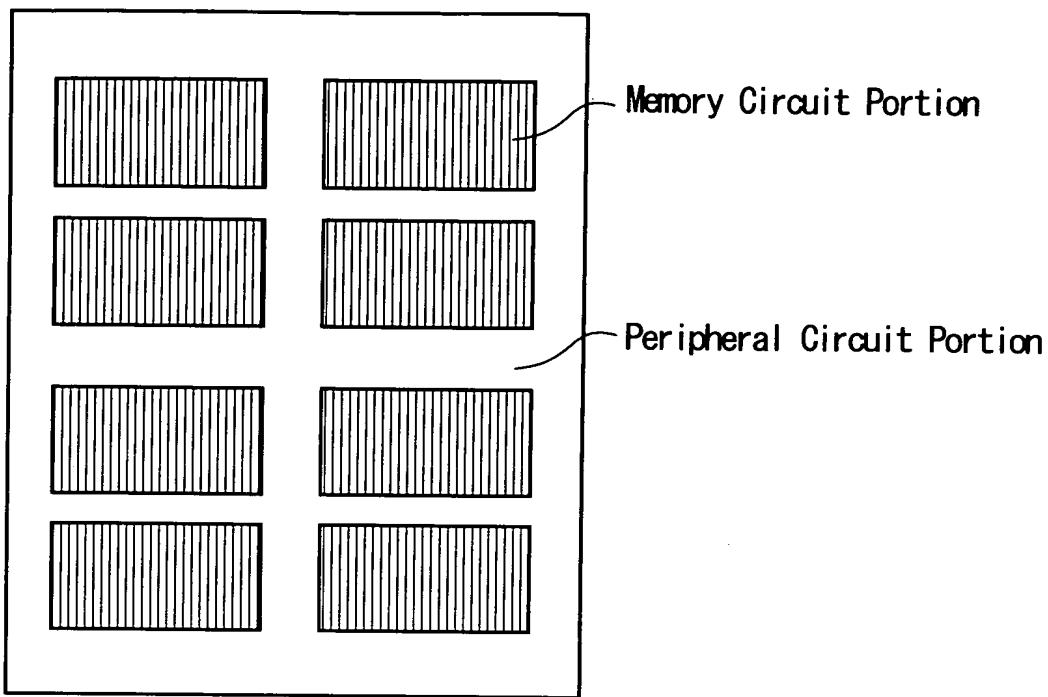
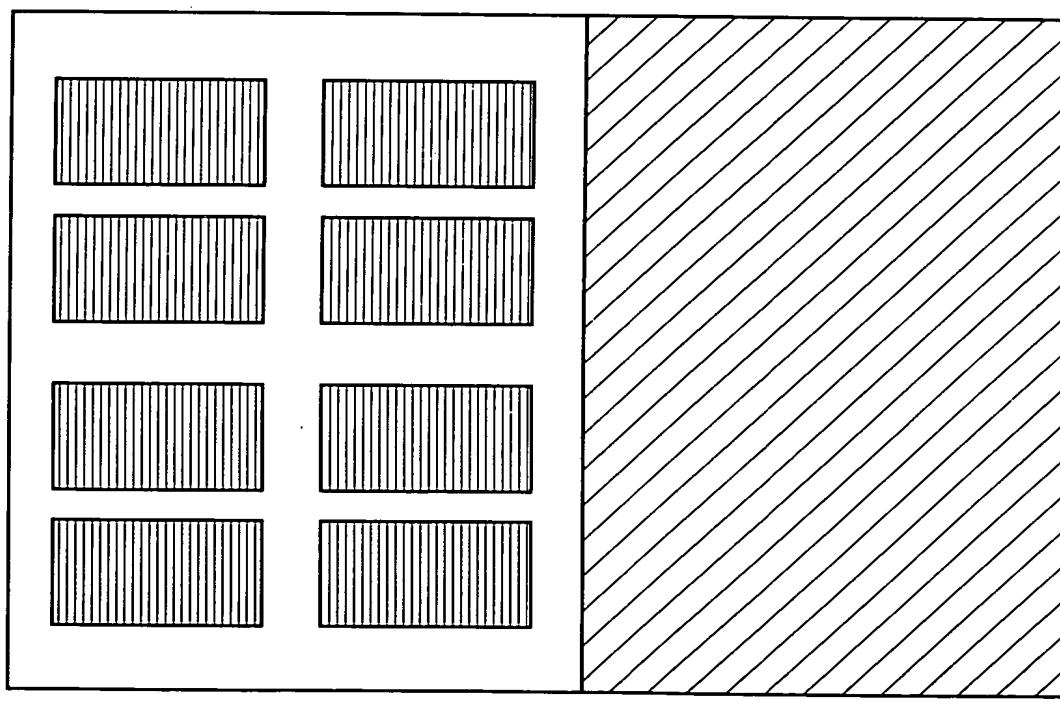


Fig. 9



Memory Circuit Portion

Logic Circuit Portion